BRAZETEC High Purity Soft Solders

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/ BRAZETEC High Purity Soft Solders

The BRAZETEC high-purity soft solder alloys offer the ideal solution for the assembly of advanced high-performance components in power electronics and microelectronics. Particularly suitable for applications such as insulated-gate bipolar transistors (IGBT) and small-outline transistors (SOT), our solders fulfill the highest quality standards. BRAZETEC pays great attention to the selection of raw materials with a high purity (4N/5N) in order to meet the demanding requirements in power electronics. The excellent quality of the BRAZETEC high-purity soft solders ensures reliable and durable solder joints and consequently outstanding performance in your electronic components.

Soft Solder Alloy Properties

Alloy Composition	$T_{Solidus}$ [°C]	$T_{Liquidus}$ [°C]	Density [g/cm³]
SnAg3Cu0,5	217	223	7,4
SnAg3Cu0,5Co0,1	219	236	7,4
SnAg3,5	221	221	7,4
SnCu3In0,5	226	300	7,4
In	156	156	7,3
InSn50	118	124	7,2
PbAg2,5	304	304	11,2
PbSn4	310	317	11,1
PbSn5	306	315	10,9
PbSn5Ag2,5	300	315	11,1

* Further alloy compositions on request

Purity:
The purity of BRAZETEC soft solder alloys is at least 99,99 % (i.e. maximum 100 ppm metallic impurities).

Standard delivery form:
The standard delivery form for soft solders is in the form of tape or perforated tape. Other delivery forms, such as preforms, wire or slugs, are available on request.